

L Number	Hits	Search Text	DB	Time stamp
1	286	platen same ring same (CMP polish\$3 planariza\$5)	USPAT	2003/11/02 16:37
2	43	platen same ring same (CMP polish\$3 planariza\$5)	EPO; JPO; DERWENT	2003/11/02 16:37
-	75287	planarization or polishing or lapping or abrading	USPAT	2003/10/31 14:56
-	5296	(planarization or polishing or lapping or abrading) and (sens\$3) same (thermocouple temperature ir infrared optical)	USPAT	2003/10/31 14:59
-	2725	((planarization or polishing or lapping or abrading) and (sens\$3) same (thermocouple temperature ir infrared optical)) and (wafer semiconductor)	USPAT	2003/10/31 15:00
-	16724	(planarization or polishing or lapping or abrading) and((sens\$3) or (thermocouple temperature ir infrared optical)) same (platen \$4table pad cloth)	USPAT	2003/10/31 15:00
-	7077	((planarization or polishing or lapping or abrading) and((sens\$3) or (thermocouple temperature ir infrared optical)) same (platen \$4table pad cloth)) and (wafer semiconductor)	USPAT	2003/10/31 15:01
-	1213	((((planarization or polishing or lapping or abrading) and((sens\$3) or (thermocouple temperature ir infrared optical)) same (platen \$4table pad cloth)) and (wafer semiconductor)) and (451/\$ 156/345.\$)	USPAT	2003/10/31 15:08
-	47	(platen turntable cloth) same (sens\$3) same (ir infrared thermocouple temperature) same (polish\$3 abrad\$3 lap\$4 planarization)	USPAT	2003/10/31 15:14
-	439	(platen turntable cloth) with(sens\$3) same (ir infrared thermocouple temperature)	USPAT	2003/10/31 15:33
-	128	156/345.14 156/345.15	USPAT	2003/10/31 15:38
-	40	156/345.16	USPAT	2003/10/31 15:38